



B8

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Tee O. Chong et al.

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED
METHODS

Docket No.: 884.419US1

Serial No.: 09/858238

Filed: May 15, 2001

Due Date: September 17, 2003

Examiner: John Vigushin

Group Art Unit: 2827

Commissioner for Patents

Notice of Allowance Date:

Attn: MAIL STOP ISSUE FEE

June 17, 2003

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the attached:

☒ A check in the amount \$ 1300.00 to cover the Large Entity Issue Fee Payment.

☒ A check in the amount of \$ 3.00 to cover the Extra Patent Copies Fee (1 copies).

☒ Issue Fee Transmittal (Form PTOL-85).

☒ A check in the amount of \$300.00 to cover the Publication Fee Payment.

☒ A return postcard.

Please charge any additional required fees for the Issue Fee Payment or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By


Charles E. Steffey

Reg. No. 25,179

CES:CMG:clh

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 31 day of July, 2003.

Chris Hammond
Name

Chris Hammond
Signature